

A 10-bit, 1.8-GS/s Time-Interleaved Pipeline ADC

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Business from technology

Outline

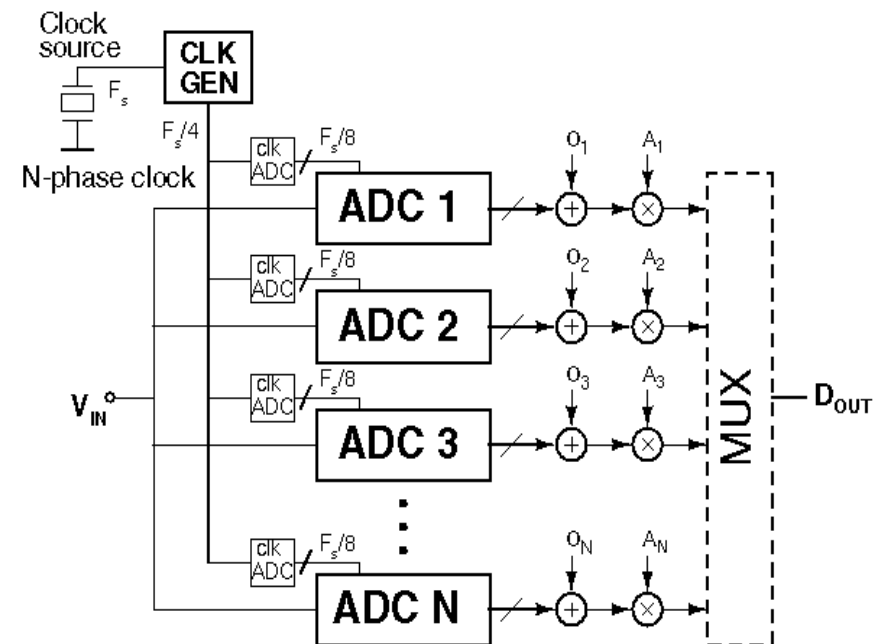
- Specifications for ADC
- Time-interleaved Pipeline ADC
 - Nonidealities, calibration
 - Architecture
 - Circuit block design
- Experimental results
- Summary

Specifications for ADC

- A satellite communicational system for ESA (European Space Agency)
- 1.8 GS/s , 10 bit resolution
- Signal bandwidth up to 500 MHz
- As low power consumption as possible
- A time- interleaved pipeline ADC topology was selected
 - A conventional flash topology was found to have too high power consumption @ 10 bit

Time-Interleaved (TI) Pipeline ADC

- Conversion rate can be increased by using time-interleaved pipeline ADC
- Resolution range (8-10 bits) suitable for pipeline topology
- Calibration is needed to overcome device mismatch and nonidealities



Nonidealities of the TI ADC, #1

- Offset

- Device mismatch in opamps
- Charge injection of sampling switches
 - Tones $f_s \cdot k/M$
 - Constant error

- Gain mismatch

- Capacitor mismatch
- Limited performance of opamp
 - Unwanted sidebands to the output spectrum
 - $\pm f_{in} \pm f_s \cdot k/M, k=1, 2, 3, \dots, M-1$

CALIBRATION

}

}

Multiplying output data by proper coefficients

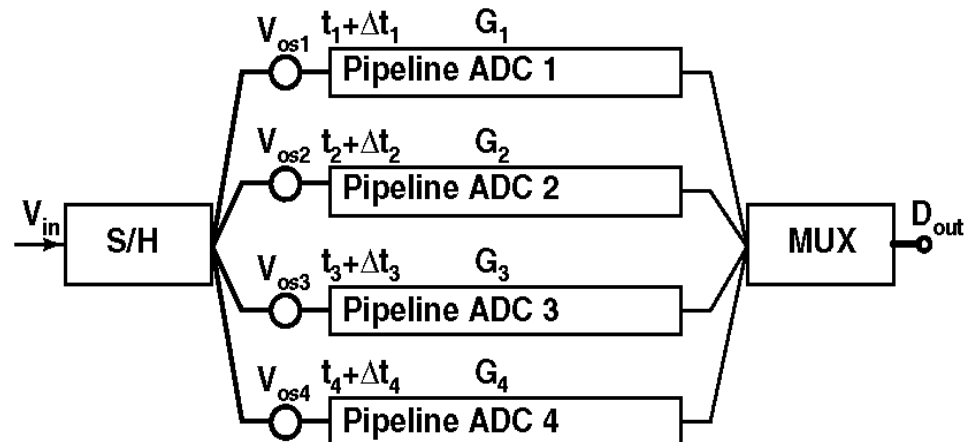
(M = number of channels)

Nonidealities of the TI ADC, #2

- Timing mismatch
 - Timing skew causes spurs at the same frequencies as gain mismatch
 - input frequency dependent
 - Can be avoided by using a full speed sample-and-hold (S/H) circuit or tunable delay locked loop (DLL)
 - Sampling clock jitter degrades SNR by increasing noise floor

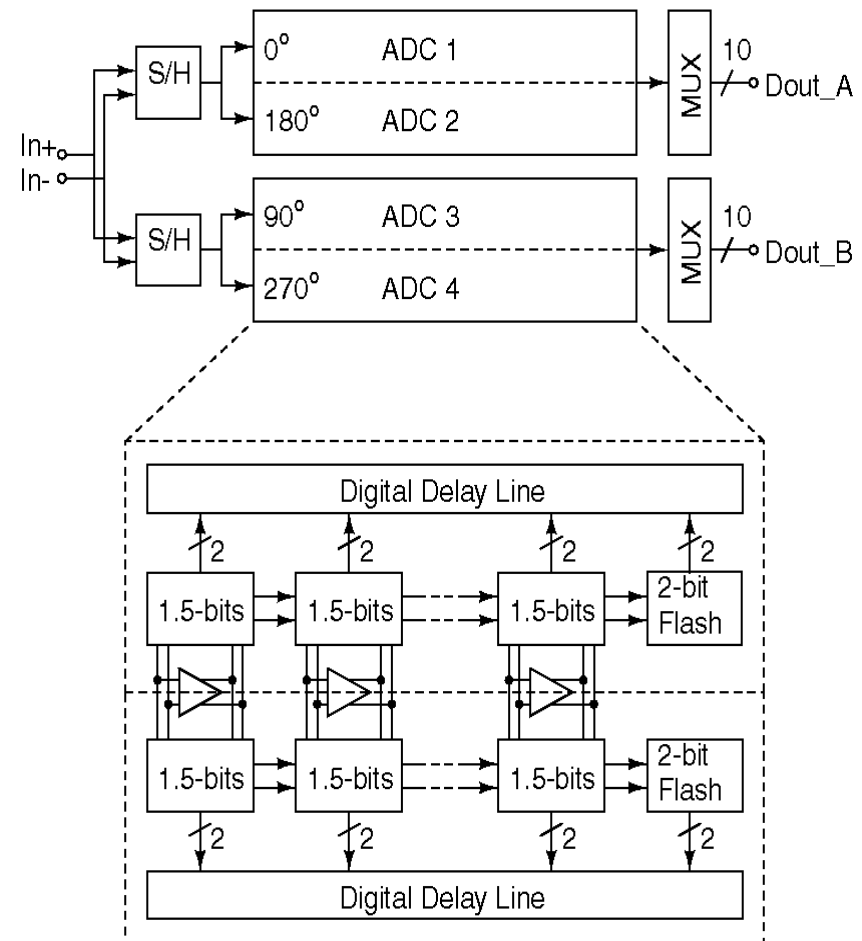
CALIBRATION

} The goal is to minimize skew in the clock path to the sampling switches
This can be done by adjusting the delay of DLL



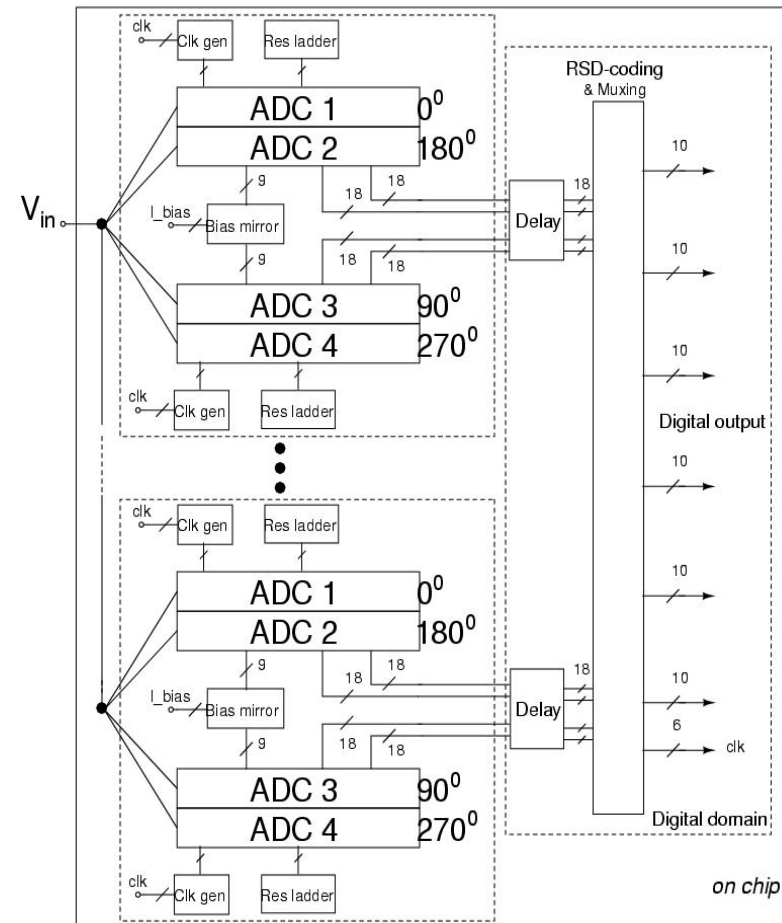
24-Channel ADC, #1

- 6x4 10-bit 80MS/s pipeline ADCs
- ADC pair utilize double-sampling and shares same front-end S/H circuit
- Resolution
 - Stage : 1.5 bits+ 2 bits (flash)
 - Number of stages : 8+1



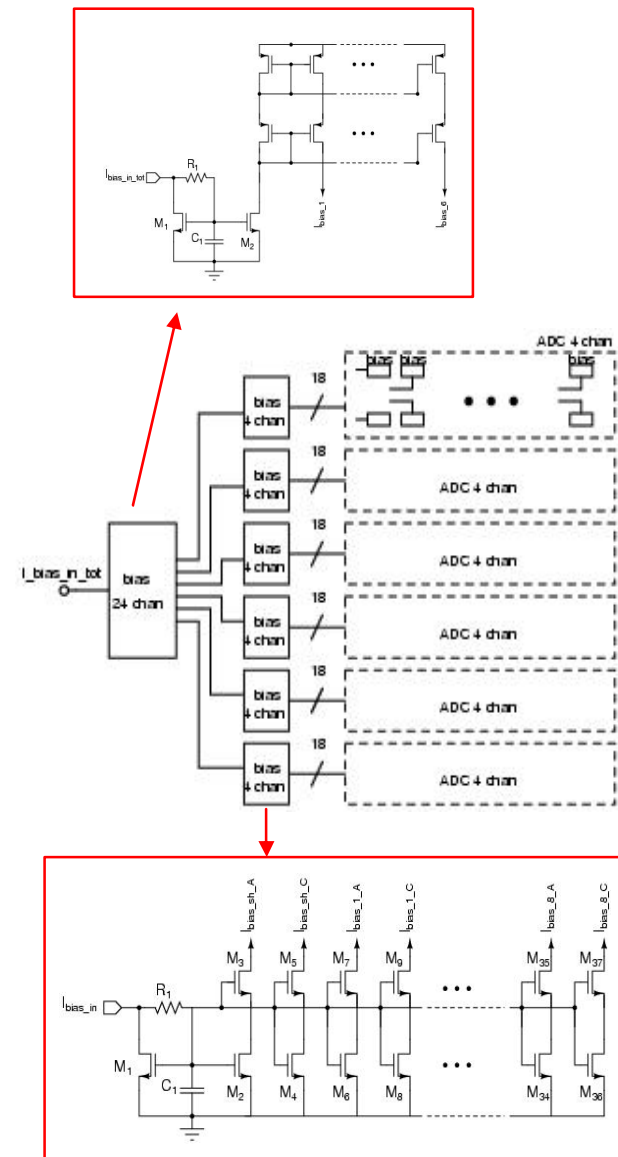
24-Channel ADC, #2

- Performance vs. power consumption
- Large die size causes problems
 - Parasitics (matching)
 - Power supply
 - Clock feedthrough



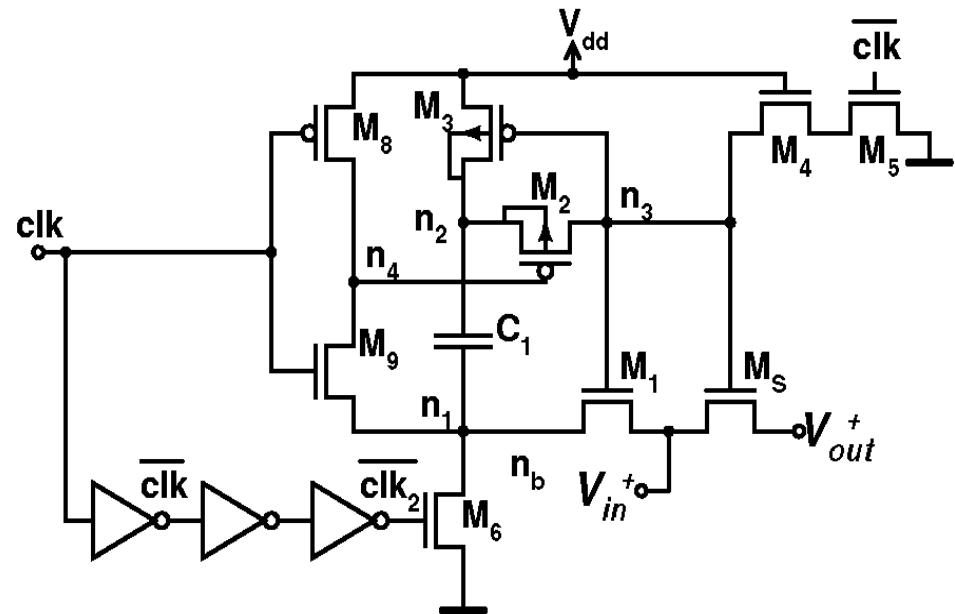
Biassing of ADC channels

- Bias circuit for each stage
- Local current mirrors for 4 channel ADCs
- Current mirrors for reference (input) current
- A single off-chip bias current
- Tolerance against parasitics from long distances



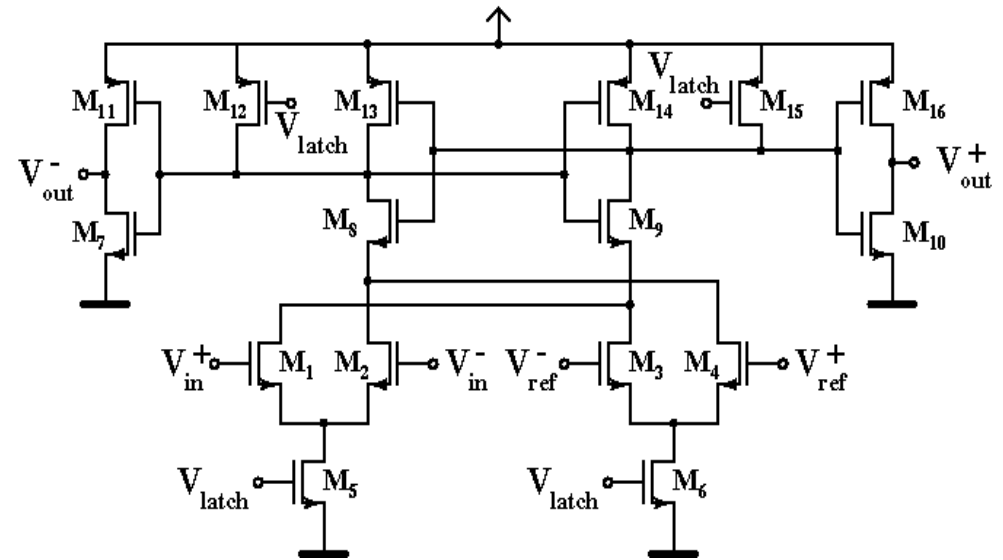
Bootstrapped Input S/H Switch

- Used in first stage as sampling switch
- Insensitive to input voltage amplitude variations
- Gate voltage of switch transistor is connected to follow the input voltage



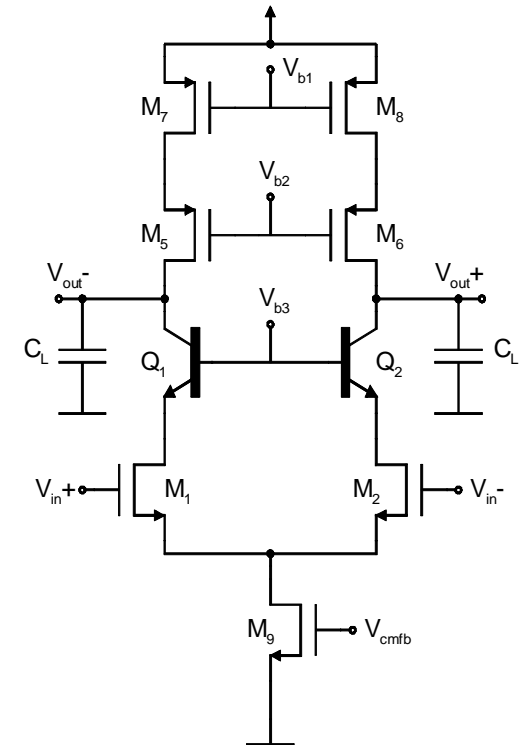
Differential pair comparator Input Switch

- A cross connected differential pairs generate a differential current
- Cross coupled inverters are used as latch
- The clock signal V_{latch} zeros the outputs every half of the clock cycle
- Benefits:
 - Fast operation & low power consumption



Operational amplifier

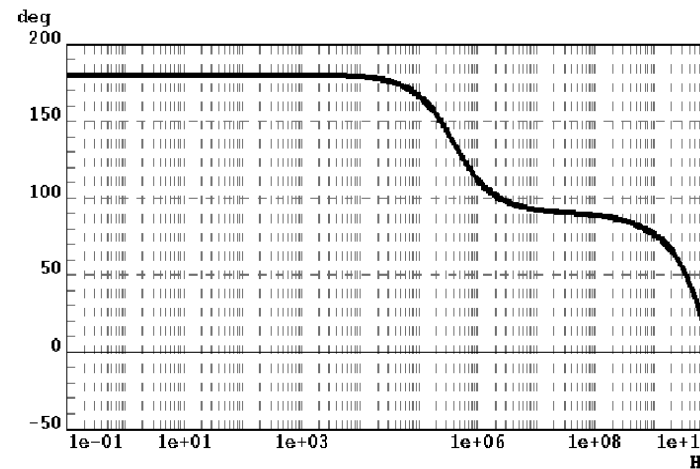
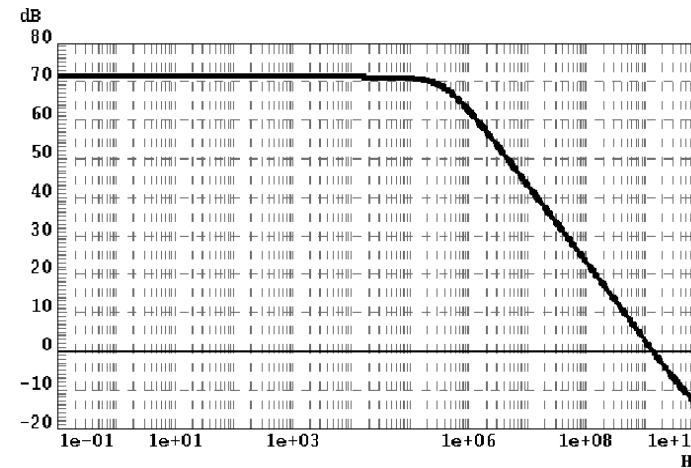
- BiCMOS telescopic OTA
- Relatively low current consumption
- The CMFB-loop is realised using standard SC-circuit
- NPN-transistors better vs. nMOS-transistors
 - Larger g_m & lower V_{sat}
- Swing is maximised by separating the common mode levels of the input and output
- Gain > 70 dB and high bandwidth can be achieved
- Slewing limited
 - determines power consumption by setting the minimum current



Operational amplifier, simulation results

- 1st stage OpAmp

PWR	6.6 mW
A_0	71 dB
GBW	1385 MHz
$V_{in,pp}$	0.5 V
PM	72.4°

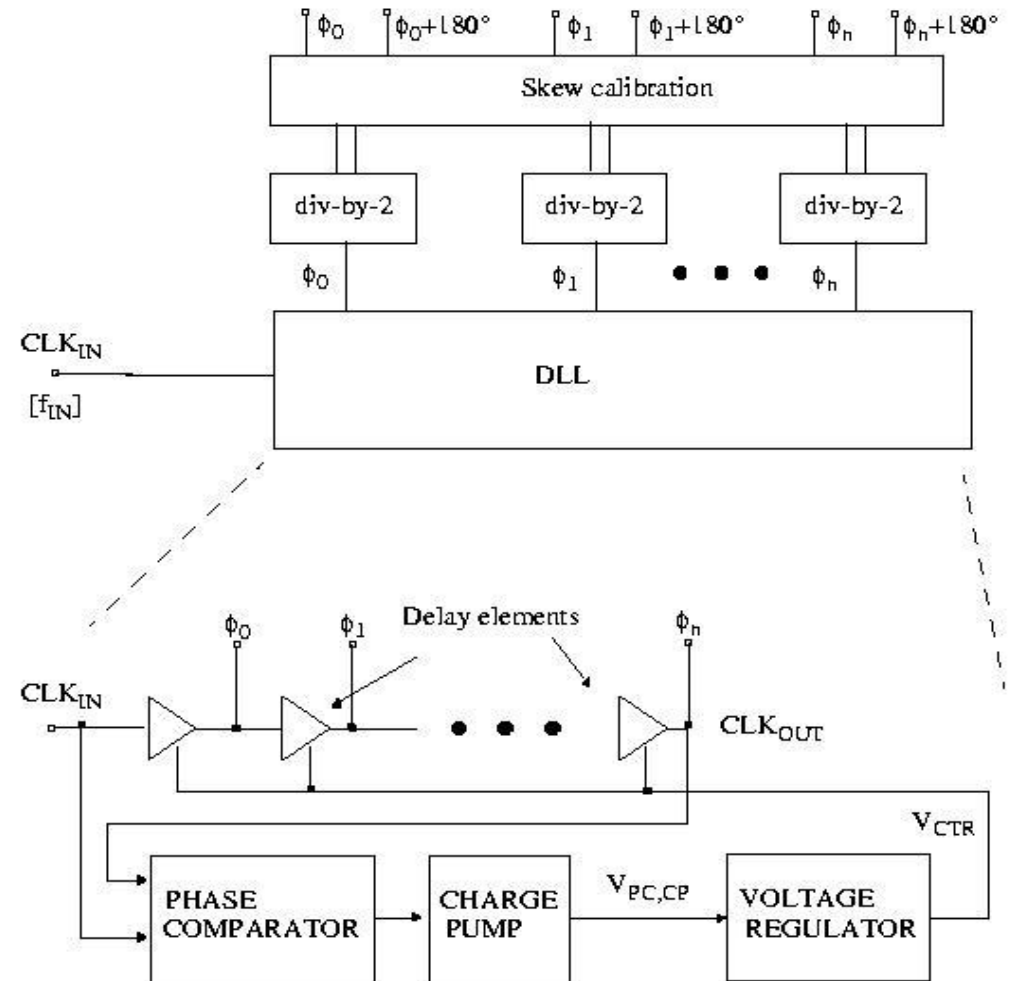


Clock generation for ADC

- 24 clock signals required
- A phase shift of 15 deg between signals
- High requirements for timing errors
 - Jitter
 - Skew
- DLL based clock generator
- Digital skew calibration for each phase

Clock generation for ADC, DLL

- A high performance external clock
 - Mtron, M650
 - 311 Mhz, Jitter below 0.5 ps (BW= 12 kHz -80 MHz)
- A DLL (delay locked loop)
 - 6 differential stages
 - Cross coupled inverters
 - div-by-2 circuits
- Digital skew calibration of each phase



Clock generation for ADC, skew calibration #1

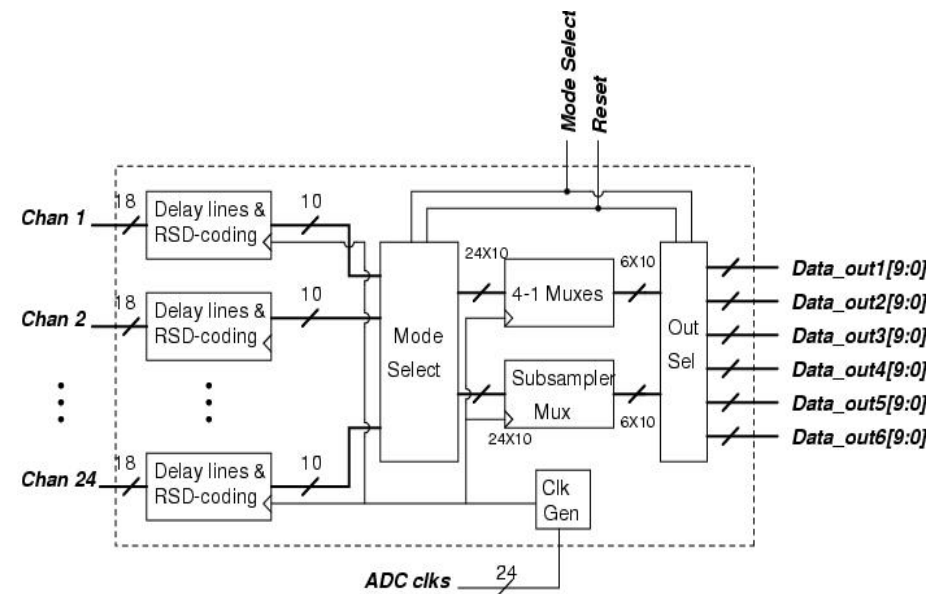
- Matching of delays between phases extremely critical
 - 0.5 ps timing accuracy required
- Delay between signals is affected by
 - Matching of active components
 - Asymmetry of parasitics (also power lines !!)
- A maximum symmetry was utilized for all components
 - Component/wiring size & orientation
 - Multiple power supply pads
 - Dummy components/wiring in all 'asymmetric' nodes

Clock generation for ADC, skew calibration #2

- Some skew elements can not be removed
 - Matching due to process tolerance
 - Asymmetric routing between DLL and ADC channels
- Delay verniers were designed for each phase signal
 - Tiny capacitors (10 fF) were coupled to signal metallization
 - Capacitive loading to signal line was altered with MOS-switch
- A 8-bit capacitance array to each line
- A resolution of 0.5 ps

Digital Domain, #1

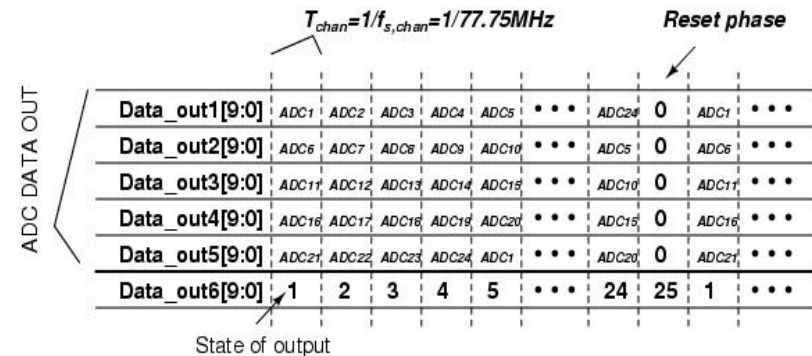
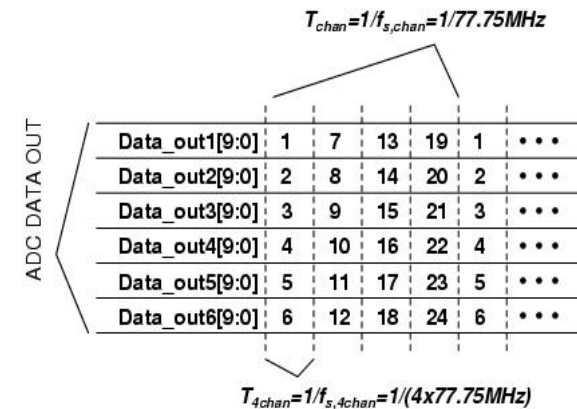
- Data synchronization
- RSD-coding
- Two alternative output modes
 - 4-to-1 muxes (@ 311MS/s)
 - Sub-sampling (@ 77MS/s)



Digital Domain, #2

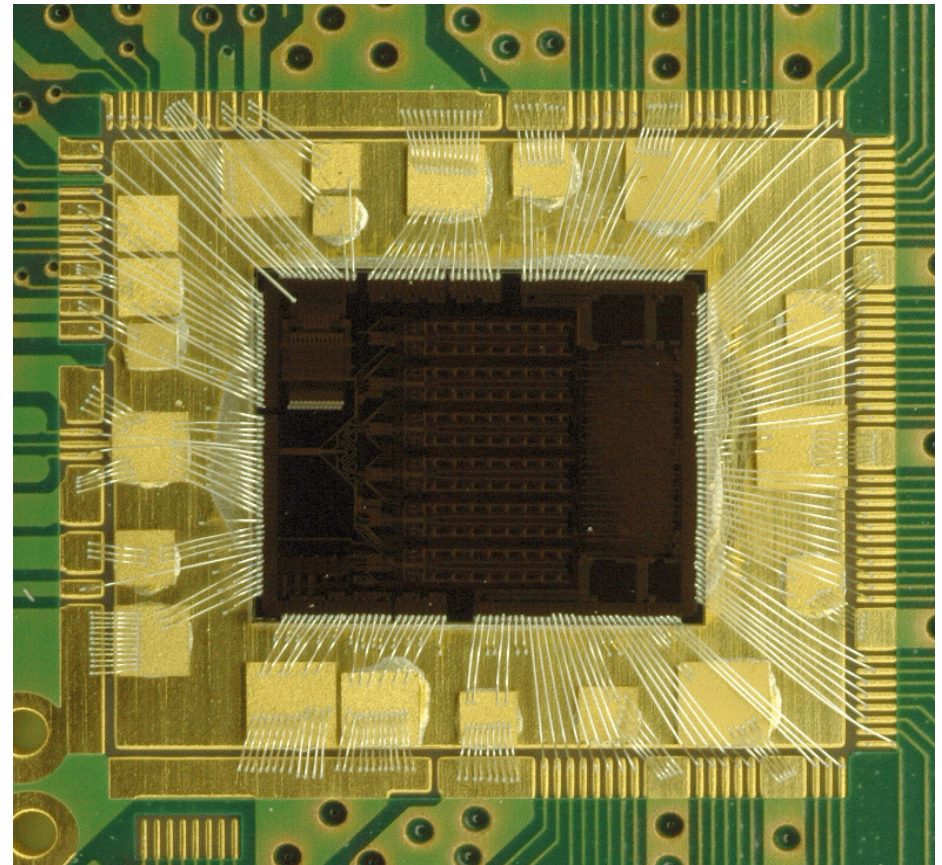
Output modes:

- High speed
 - 4-to-1 muxing
 - ~ 320 MS/s data rate
 - Sensitive to process variations, temperature
- Sub-sampling
 - Every 5th sample is driven to outputs



Experimental results, background

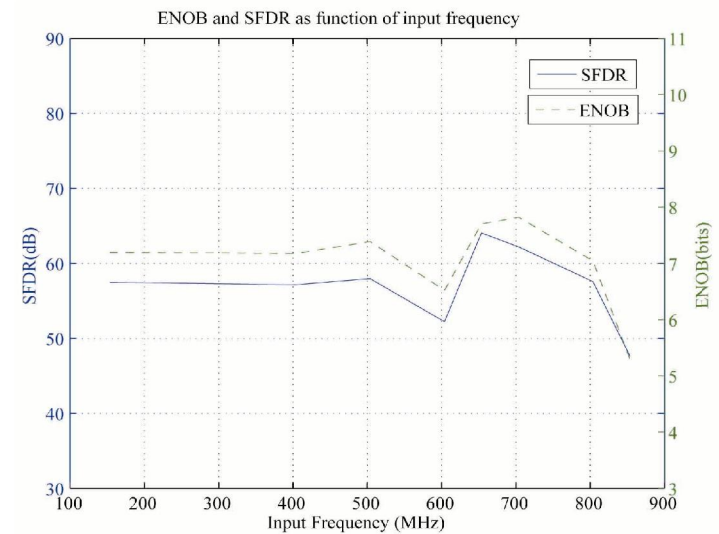
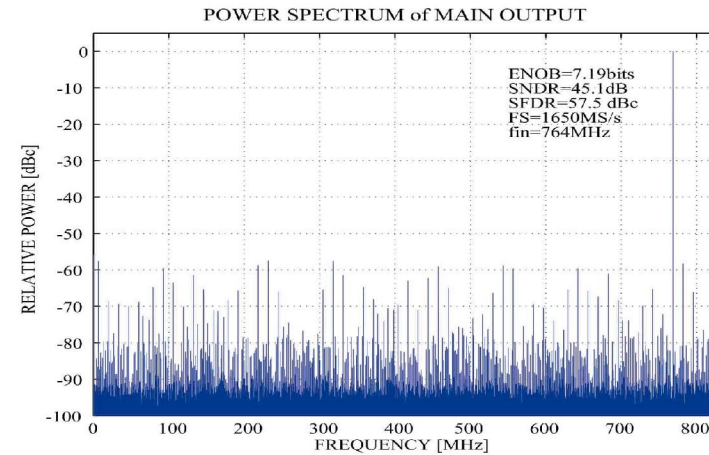
- A 0.35 μm SiGe BiCMOS technology (AMS)
 - BJT's were only utilized in OPAMP's
- Area 5.8 x 6.9 mm²,
- 215.000, devices
- Wirebonded directly to PCB
 - 4 layer, fine pitch
 - Microcaps for decoupling supplies
 - A heat sink applied top of gloptop



Experimental results, summary(1)

TABLE I. PERFORMANCE SUMMARY

Resolution	10 bits
Sample Rate	1.8GS/s
Power cons.	3.5W
SFDR	
@ $f_{in}=29.7\text{MHz}$	66.2dB
@ $f_{in}=764\text{MHz}$	57.5dB
ENOB	
(@ $f_{in}=29.7\text{MHz}$)	8.31 bits
(@ $f_{in}=764\text{MHz}$)	7.19 bits
Technology	0.35- μm BiCMOS
Area	5.8x6.9 mm^2



Experimental results, summary (2)

- Power consumption 3.5...3.9 W
 - analog part 2.2...2.6 W (variation from chip to chip)
 - digital part 1.3...1.8 W
 - depends heavily on switching frequency of the data
 - main power eater: output pad buffers
 - the circuit at the limits of the process digital performance
- Calibration: manual
 - for a production version on-chip calibration circuit recommended

Experimental results, summary (3)

- Yield and Reliability
 - *the circuit is not radiation tested*
 - large chip \rightarrow limited yield?
 - high power \rightarrow high operating temperature
 - needs a heat sink
 - reduces performance in terms of SNR
 - increases gain errors
 - circuit at the speed limit of the process
 - variations and changes in the delays critical
 - parasitic capacitances limit the pipeline performance
 - and define the maximum reasonable analog power consumption
 - the process has only 4 metal layers
 - analog power supply lines non-symmetrical
 - non-optimum data or clock lines

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